



Product Overview

Focus Tech TSOx-3001

Tin/Solder Stripper

Product Description

TSOx-3001 is an ammonium bifluoride/hydrogen peroxide based tin/solder stripper. TSOx-3001 can be used in spray or immersion and for either full panel or tab stripping applications. TSOx-3001 is excellent for selective solder stripping applications where nickel/gold plating is present because it will not attack the nickel plating and cause gold slivers. TSOx-3001 strips tin/solder quickly and leaves the underlying copper surface clean, residue free and ready for subsequent processing. TSOx-3001 can be replenished with technical grade hydrogen peroxide to extend bath life.

Features

- ⊙ Hydrogen peroxide replenishable
- ⊙ Rate enhancing additives
- ⊙ Low copper attack

Benefits

- ⊙ Low operating costs
- ⊙ Increases strip rate without increasing consumption
- ⊙ Superior surface cosmetics

Operating Parameters

Concentration:	100%
Temperature:	70 °F – 90 °F
Dwell time:	0.5 – 2 minutes
Ventilation:	recommended
Hydrogen Peroxide:	6% - 8% hydrogen peroxide (as 50% H ₂ O ₂)

Storage

Store in original containers above 40 °F.

Safety

CAUTION! TSOX-3001 contains oxidizing acidic components. Avoid contact with eyes, skin and clothing. Wear chemical handler's gloves, goggles and protective clothing when handling. Read and understand Material Safety Data Sheet before using this product.

Notice

The information and recommendations, contained herein, regarding this product are, to the best of our knowledge, true and accurate. We make no guarantee of results because the conditions of actual use are beyond our control. We assume no liability for damages or penalties resulting from the use of this product or following our recommendations. Our recommendations and suggestions for use of this product are not intended to grant license to operate under or infringe any patent.